

PARALLEL ALIGNMENT METHOD AND APPARATUS FOR CHEMICAL MECHANICAL POLISHING

ABSTRACT OF THE DISCLOSURE

10

A chemical mechanical polishing apparatus is provided. The apparatus includes a single polishing pad and a leaf structure having a pair of fingers. Each finger holds a carrier device designed to hold a wafer to be polished. The leaf structure is configured to apply each of the wafers onto the single polishing pad.

37162626 2009-06-26